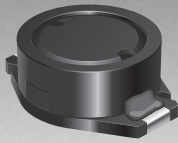


*RoHS COMPLIANT



BOURNS®

Features

- Available in E12 series
- Unit height of 6.8 mm
- Current up to 8 A Isat
- RoHS compliant*

Applications

- Input/output of DC/DC converters
- Power supplies for:
 - Portable communication equipment
 - Camcorders
 - LCD TVs
 - Car radios

SRR1806 Series - Shielded Power Inductors

Electrical Specifications

Bourns Part No.	Inductance 100 kHz		Q Ref.	Test Frequency (MHz)	SRF Typ. (MHz)	RDC $\pm 20\%$ (Ω)	I rms Max. (A)	I sat Typ. (A)
	(μ H)	Tol. %						
SRR1806-100M	10.0	± 20	56	2.52	19.0	0.033	4.00	8.20
SRR1806-150M	15.0	± 20	53	2.52	17.5	0.039	3.60	7.20
SRR1806-220M	22.0	± 20	51	2.52	16.0	0.053	3.00	6.20
SRR1806-330M	33.0	± 20	44	2.52	10.0	0.083	2.50	5.00
SRR1806-470M	47.0	± 20	40	2.52	8.0	0.110	2.00	4.20
SRR1806-680M	68.0	± 20	37	2.52	6.0	0.170	1.60	3.40
SRR1806-101M	100.0	± 20	40	0.796	4.6	0.270	1.30	2.60
SRR1806-151M	150.0	± 20	39	0.796	4.3	0.400	1.05	2.30
SRR1806-221M	220.0	± 20	29	0.796	3.5	0.510	1.00	1.90
SRR1806-331M	330.0	± 20	30	0.796	3.0	0.790	0.80	1.40
SRR1806-471M	470.0	± 20	27	0.796	2.4	1.000	0.64	1.30
SRR1806-681M	680.0	± 20	19	0.796	2.1	1.470	0.54	1.10
SRR1806-102M	1000.0	± 20	46	0.796	1.5	2.160	0.45	0.90

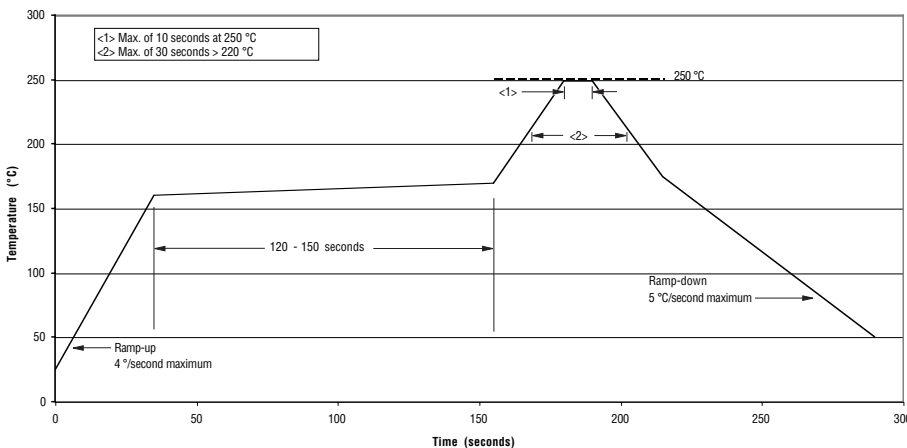
General Specifications

Test Voltage.....0.1 V
 Reflow soldering.....250 °C; 10 sec max.
 (In compliance with JEDEC, J-STD-020C, Table 4-2)
 Operating Temperature ..-40 °C to +125 °C
 (Temperature rise included)
 Storage Temperature..-45 °C to +125 °C
 Resistance to Soldering Heat
250 °C, 10 sec. max.

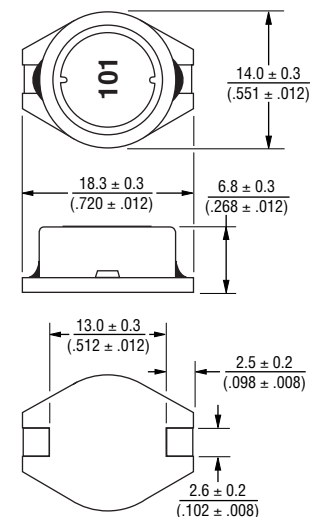
Materials

Core.....Ferrite core
 Wire.....Enameled copper
 BaseLCP E4008
 TerminalCu/Ni/Sn
 Rated Current Ind. drop 10 % typ. at Isat
 Temperature Rise
40 °C max. at rated I rms
 Packaging.....250 pcs. per reel

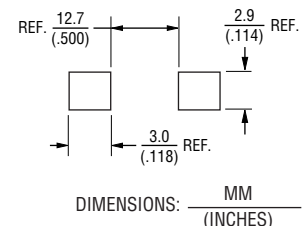
Soldering Profile



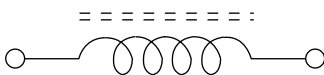
Product Dimensions



Recommended Layout



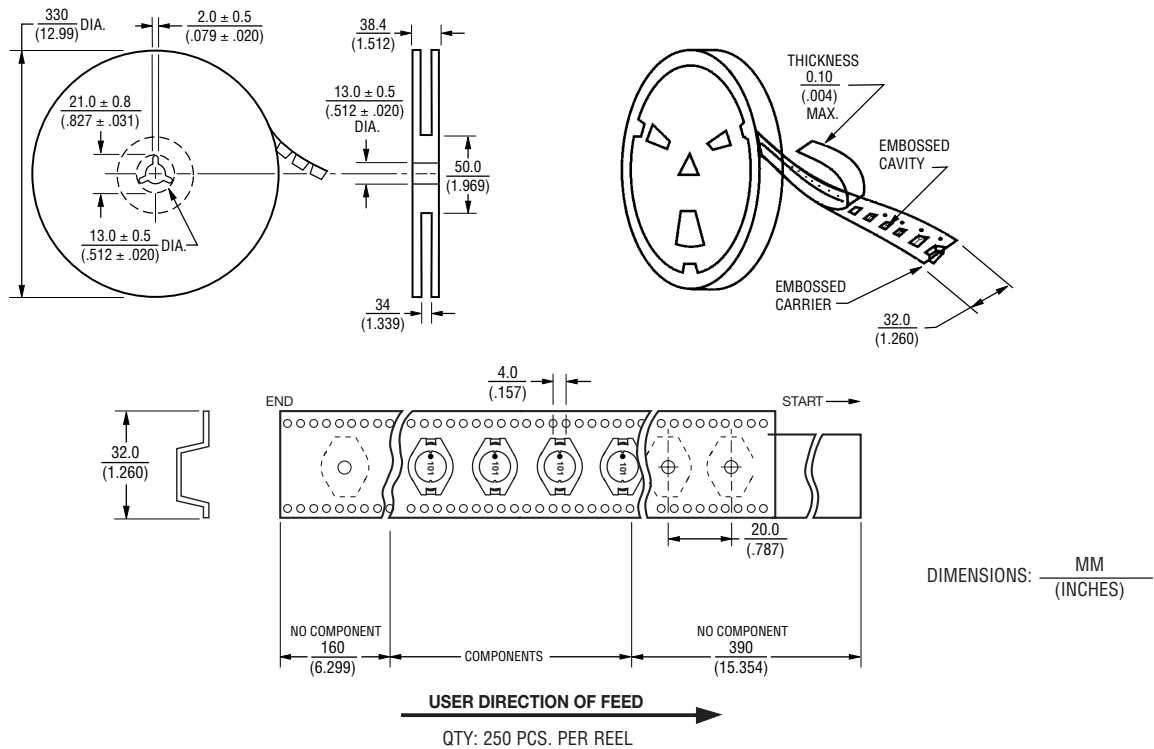
Electrical Schematic



SRR1806 Series - Shielded Power Inductors

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Packaging Specifications



REV. 05/11

Specifications are subject to change without notice.

Customers should verify actual device performance in their specific applications.